

GOVERNMENT OF INDIA
MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY
LOK SABHA
STARRED QUESTION NO. *65
TO BE ANSWERED ON: 04.02.2026

DOMESTIC MANUFACTURING OF CRITICAL ELECTRONIC COMPONENTS

***65. SHRI PRAVEEN KHANDELWAL:**

Will the Minister of ELECTRONICS AND INFORMATION TECHNOLOGY be pleased to state:

- (a) whether a national framework exists to promote domestic manufacturing of critical electronic components beyond assembly; and
- (b) if so, the details of steps taken to reduce strategic import dependence?

ANSWER

MINISTER OF ELECTRONICS AND INFORMATION TECHNOLOGY
(SHRI ASHWINI VAISHNAW)

(a) and (b): A Statement is laid on the Table of the House.

STATEMENT REFERRED TO IN THE REPLY TO LOK SABHA STARRED QUESTION NO. *65 FOR 04.02.2026, REGARDING DOMESTIC MANUFACTURING OF CRITICAL ELECTRONIC COMPONENTS

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(a) and (b): Government of India's semiconductor strategy is based on Prime Minister's vision of Make in India and Atmanirbhar Bharat. This is a well thought out strategy to develop manufacturing from finished product assembly, sub-assembly, components, chip design, fabrication, packaging etc.

Electronics manufacturing in India has expanded significantly in the last 11 years. It can be seen from the following statistics:

#	2014-15	2024-25	Remarks
Production of electronics goods (Rs.)	~1.9 Lakh Cr	~11.3 Lakh Cr	Increased 6 times
Export of electronics goods (Rs.)	~0.38 Lakh Cr	~3.3 Lakh Cr	Increased 8 times
Production of mobile phones (Rs.)	~0.18 Lakh Cr	~5.5 Lakh Cr	Increased 28 times
Export of mobile phones (Rs.)	~0.01 Lakh Cr	~ 2 Lakh Cr	Increased 127 times

To further deepen the Value Chain, Government recently launched Electronics Components Manufacturing Scheme (ECMS). The scheme aims to develop manufacturing of key components such as Printed Circuit Boards (PCBs), passive components, electro-mechanical components, sub-assemblies, camera modules, optical transceivers, and capital goods required for electronics manufacturing.

The ECMS has received unprecedented response from the industry so far. Against the initial investment target of Rs. 59,350 crore, industry has submitted 249 proposals with total investment commitment of Rs. 1.15 lakh crore. Encouraged by the response, ECMS outlay has also been increased from Rs. 22,900 Cr to Rs. 40,000 Cr. in Budget 2026-27.

The approved applicants would manufacture a wide spectrum of electronic components such as aluminium extrusion, anode material, camera modules, capacitors, connectors, display modules, enclosures for mobile and IT hardware products and related devices, laminates, li-ion cells, optical transceivers, oscillators, PCBs (multi-layer & HDI), and polypropylene film. These components are expected to be used across various sectors such as consumer electronics, telecom, automotive electronics, strategic electronics, mobile phones, and IT hardware.

To develop semiconductor manufacturing and to further widen the supply chain ecosystem with respect to manufacturing of active electronics component, Government of India launched Semicon India Program in 2022. Government is focused on developing the entire value chain of semiconductors which includes - designing, fabrication, assembly, testing and packaging.

- In less than 3 years, ten (10) units have been approved with cumulative investment of Rs 1.6 Lakh Crore. These units include silicon fab, Silicon Carbide fab, advanced packaging, memory packaging, etc. These would cater to chip requirements of sectors such as consumer appliances, industrial electronics, automobiles, telecommunications, aerospace, and power electronics etc.
- For chip design, 24 projects have been approved under the Design Linked Incentive Scheme for financial support to design semiconductor chips for critical sectors such as video surveillance, drone detection,

energy metering, microprocessors, satellite communications, broadband technologies, and SoC for the Internet of Things (IoT).

- Government is following a strategic path to provide free access of Design Infrastructure Support with access to advanced chip design tools, intellectual property (IP) cores, multi-project wafer (MPW) fabrication services, and prototyping facilities to academia, startups and MSMEs.

Union Budget for 2026-27 has also announced Semicon 2.0 to further expand semiconductor manufacturing ecosystem.
